



### Analysis Report - 1000-16793

<b>Customer Name:</b>	BOMINGFEI ELECTRONICS CO.LTD	<b>Purchase Order:</b>	20180719
<b>Part Number:</b>	EPCS4S18N	<b>Lot/Date Code:</b>	06254
<b>Manufacturer:</b>	ALTERA	<b>Devices Received:</b>	1

#### Summary Of Inspection Results

Test-Process Operation	Quantity Inspected	Pass	Fail	Date	N/A	Comments / Observations
Documentation and Packaging (SAE AS6081, 4.2.6.4.1) (Non-destructive)						
Condition Observed	1	1	0	2018-07-19		Total 1pcs was received in bag format.
Delid/Decapsulation Internal Analysis (AS6081 4.2.6.4.6) or (MIL-STD-883, Method 2014) (Destructive)						
Die Verification	1	0	1	2018-07-19		1 sample was decapsulated. Die logo is MIAMI4M 2013 - 0323. Die topography and marking does not correlate to known good sample in GETS data base. Device confirmed to be not authentic and not recommend to be use in any application.

<b>Prepared by:</b> Xu, Jay X.	<b>Disclaimer</b> Global Electronics Testing Services, LLC China is dedicated to ensuring the highest standard of product testing in the industry and extend every effort to report reliable data and an accurate interpretation. However in no event shall Global Electronics Testing Services, LLC China be liable any special, indirect or consequential damages or any damages whatsoever resulting from loss of any kind including profits, in any action arising out of or in connection with the test report or data associated with the report.	<b>Generated On:</b> Jul 20, 2018 00:03:21
<b>Approved by:</b> Yan, Peter X.	<b>Global Electronics Testing Services   Futian District, Shenzhen China   86-0755-82911501</b>	<b>Page:</b> Page 1 Of 3



## Analysis Report - 1000-16793

<b>Customer Name:</b>	BOMINGFEI ELECTRONICS CO.LTD	<b>Purchase Order:</b>	20180719
<b>Part Number:</b>	EPCS4SI8N	<b>Lot/Date Code:</b>	06254
<b>Manufacturer:</b>	ALTERA	<b>Devices Received:</b>	1

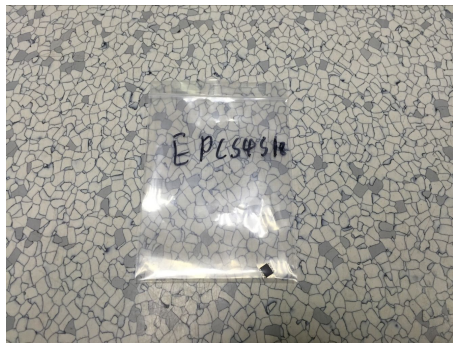
### Documentation and Packaging (SAE AS6081, 4.2.6.4.1) (Non-destructive)

#### Results Summary

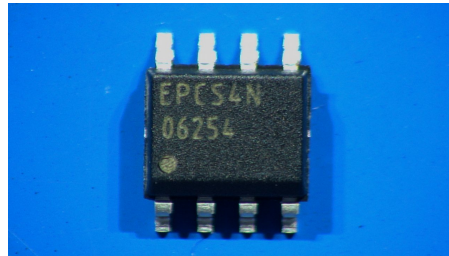
Total 1pcs was received in bag format.

Criteria	Acceptable	Suspect	Not Acceptable	N/A	Comments / Observations
<b>Incoming Conditions</b>					
ESD Protection				X	
Poor Syntax or Alterations				X	Manufacturer label is not available
Correct MSL Packaging				X	
Quantity Match Document	X				1pcs in bag format
Box Damaged				X	
Type of Package	X				Bag format

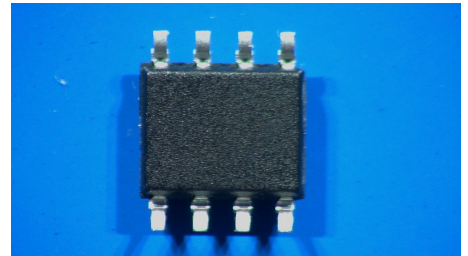
### Images For Documentation and Packaging .



**Figure 1.** RECEIVED




**Figure 2.** TOP



**Figure 3.** BOTTOM

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	<b>Manufacturer:</b>	ALTERA	<b>Devices Received:</b>	1

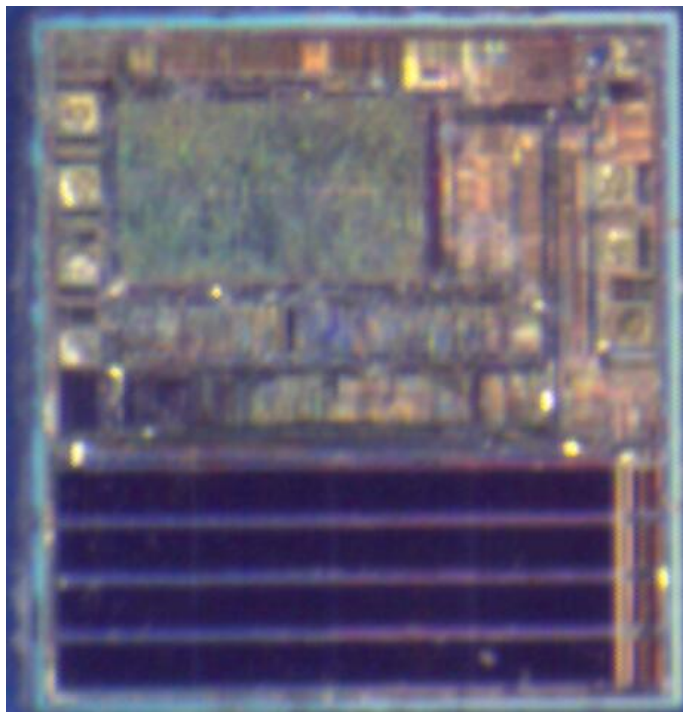
Delid/Decapsulation Internal Analysis (AS6081 4.2.6.4.6) or (MIL-STD-883, Method 2014) (Destructive)

**Results Summary**

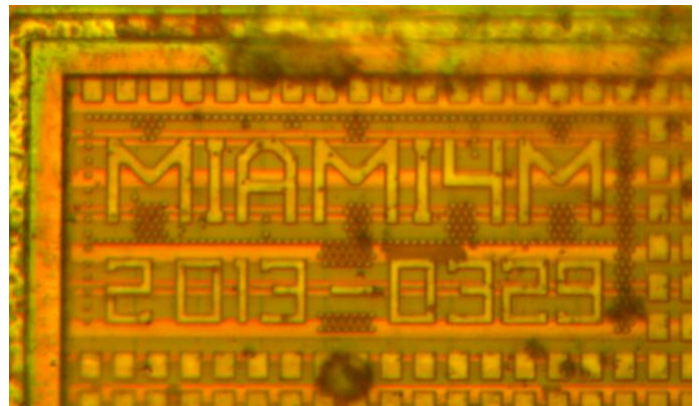
1 sample was decapsulated. Die logo is MIAMI4M 2013 - 0323. Die topography and marking does not correlate to known good sample in GETS data base. Device confirmed to be not authentic and not recommend to be use in any application.

Criteria	Acceptable	Suspect	Not Acceptable	N/A	Comments / Observations
Internal Visual Inspection					
Die Topography			X		
Die Markings			X		

**Images For Delid/Decapsulation Internal Analysis.**



**Figure 4. DIE**



**Figure 5. DIE MARKING**

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